

N-Channel Power MOSFET

600V, 51A, 69mΩ

FEATURES

- Latest super-junction technology
- Low gate charge capacitance
- High gate noise immunity
- RoHS compliant
- Halogen-free

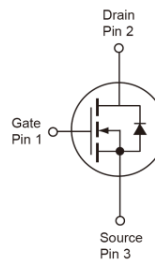
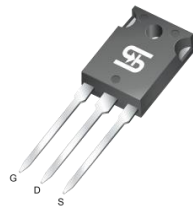
KEY PERFORMANCE PARAMETERS		
PARAMETER	VALUE	UNIT
V_{DS}	600	V
$R_{DS(on)}$ (max)	69	mΩ
Q_g	86	nC

APPLICATIONS

- Switching applications
- HV motor driver
- Industrial



TO-247



ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V_{DS}	600	V
Gate-Source Voltage	V_{GS}	±30	V
Continuous Drain Current	I_D	51	A
$T_C = 25^\circ\text{C}$			
Pulsed Drain Current (Note 1)	I_{DM}	204	A
Total Power Dissipation @ $T_C = 25^\circ\text{C}$	P_D	417	W
Single Pulse Avalanche Energy (Note 2)	E_{AS}	780	mJ
Single Pulse Avalanche Current (Note 2)	I_{AS}	5.6	A
Operating Junction and Storage Temperature Range	T_J, T_{STG}	- 55 to +150	°C

THERMAL PERFORMANCE

PARAMETER	SYMBOL	LIMIT	UNIT
Junction to Case Thermal Resistance	$R_{\theta JC}$	0.3	°C/W
Junction to Ambient Thermal Resistance (Note 3)	$R_{\theta JA}$	50	°C/W

Notes:

1. Pulse Width ≤ 100μs.
2. L = 50mH, R_G = 25Ω, Starting T_J = 25°C.
3. R_{θJA} is the sum of the junction-to-case and case-to-ambient thermal resistances. R_{θJA} is guaranteed by design while R_{θJA} is determined by the user's board design.

ELECTRICAL SPECIFICATIONS ($T_A = 25^\circ\text{C}$ unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
Static (Note 4)						
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 1mA$	BV_{DSS}	600	--	--	V
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 3.5mA$	$V_{GS(TH)}$	4	4.8	6	V
Gate Body Leakage	$V_{GS} = \pm 30V, V_{DS} = 0V$	I_{GSS}	--	--	± 100	nA
Zero Gate Voltage Drain Current	$V_{DS} = 600V, V_{GS} = 0V$	I_{DSS}	--	--	100	μA
Drain-Source On-State Resistance	$V_{GS} = 10V, I_D = 17A$	$R_{DS(on)}$	--	55	69	m Ω
	$V_{GS} = 12V, I_D = 17A$		--	52	60	
Dynamic (Note 5)						
Total Gate Charge	$V_{DS} = 480V, I_D = 51A,$ $V_{GS} = 10V$	Q_g	--	86	--	nC
Gate-Source Charge		Q_{gs}	--	27	--	
Gate-Drain Charge		Q_{gd}	--	50	--	
Input Capacitance	$V_{DS} = 300V, V_{GS} = 0V,$ $f = 100kHz$	C_{iss}	--	3566	--	pF
Output Capacitance		C_{oss}	--	99	--	
Reverse Transfer Capacitance		C_{rss}	--	6	--	
Gate Resistance	$f = 1.0Hz$	R_g	--	0.9	--	Ω
Switching (Note 6)						
Turn-On Delay Time	$V_{DD} = 300V, R_G = 3.3\Omega,$ $I_D = 51A, V_{GS} = 10V$	$t_{d(on)}$	--	49	--	ns
Turn-On Rise Time		t_r	--	66	--	
Turn-Off Delay Time		$t_{d(off)}$	--	80	--	
Turn-Off Fall Time		t_f	--	37	--	
Source-Drain Diode						
Forward Voltage (Note 4)	$I_S = 17A, V_{GS} = 0V$	V_{SD}	--	0.9	1.5	V
Reverse Recovery Time	$I_S = 25.5A$	t_{rr}	--	465	--	ns
Reverse Recovery Charge	$di/dt = 100A/\mu s$	Q_{rr}	--	10	--	μC

Notes:

- Pulse test: Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- Defined by design. Not subject to production test.
- Switching time is essentially independent of operating temperature.

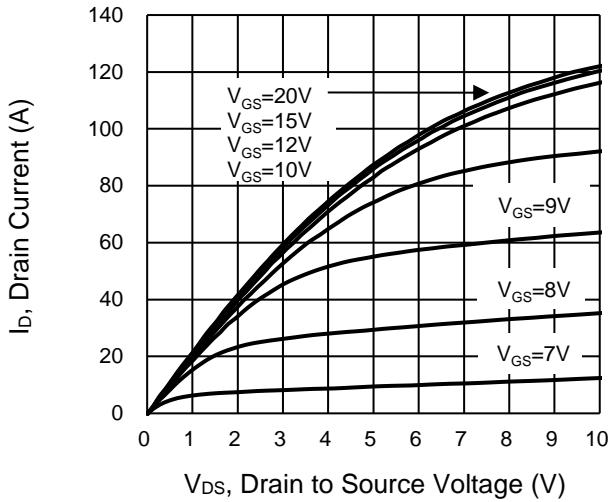
ORDERING INFORMATION

ORDERING CODE	PACKAGE	PACKING
TSM60NE069PW C0G	TO-247	30pcs / Tube

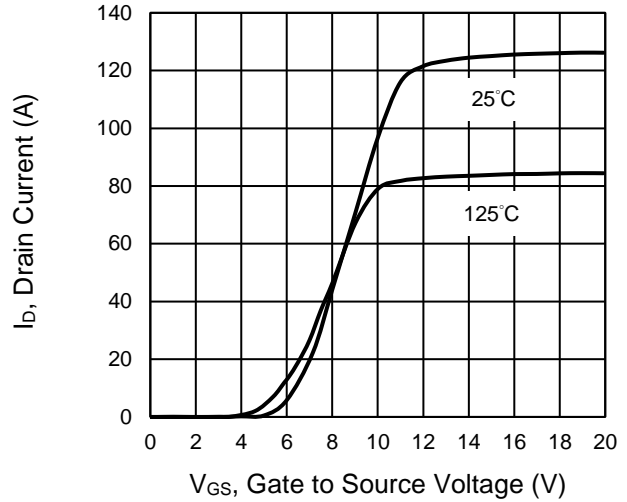
CHARACTERISTICS CURVES

(T_c = 25°C unless otherwise noted)

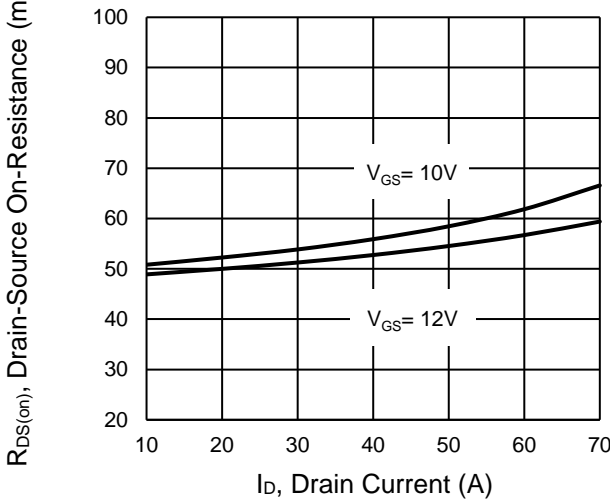
Output Characteristics



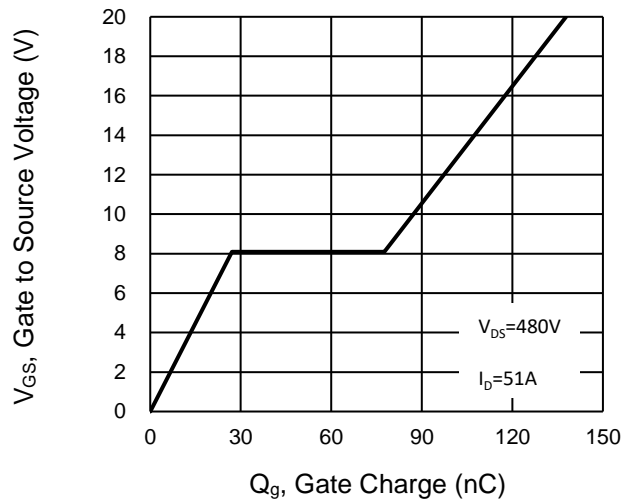
Transfer Characteristics



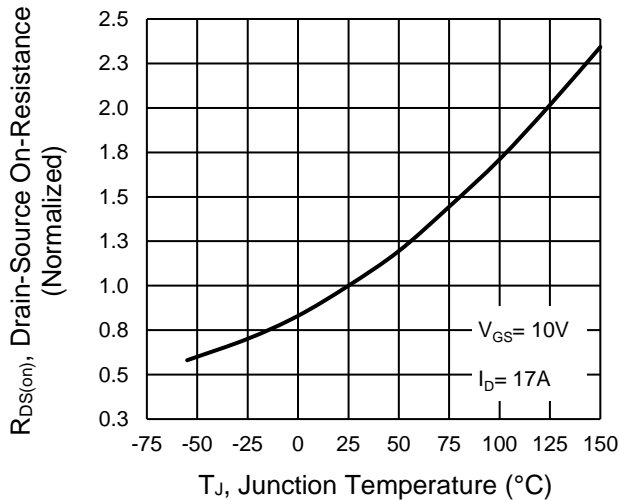
On-Resistance vs. Drain Current



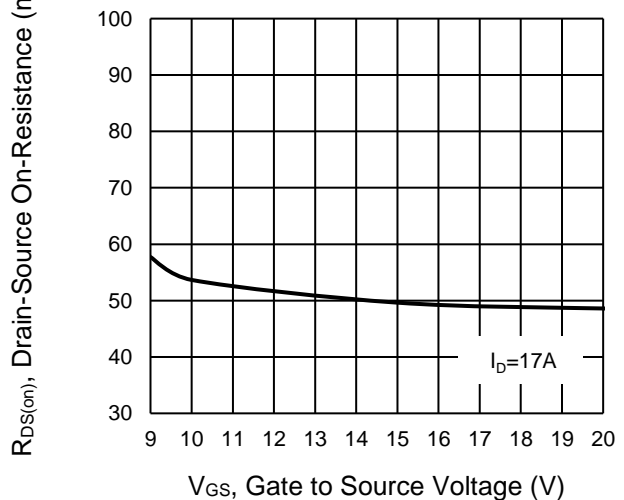
Gate-Source Voltage vs. Gate Charge



On-Resistance vs. Junction Temperature



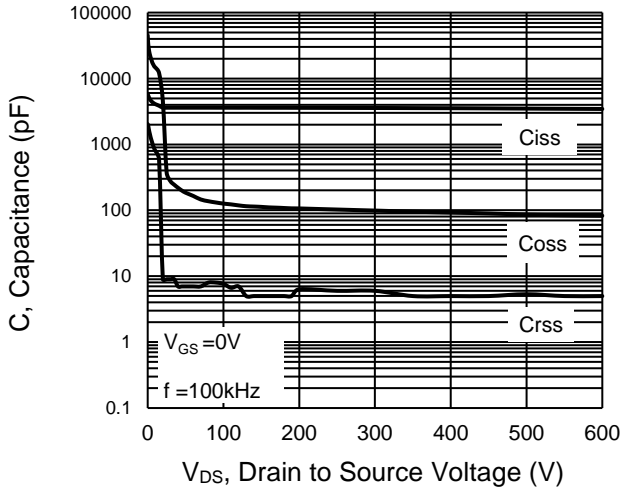
On-Resistance vs. Gate-Source Voltage



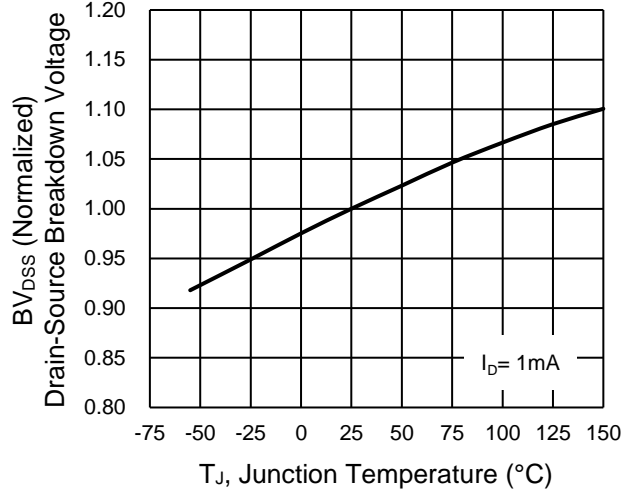
CHARACTERISTICS CURVES

($T_c = 25^\circ\text{C}$ unless otherwise noted)

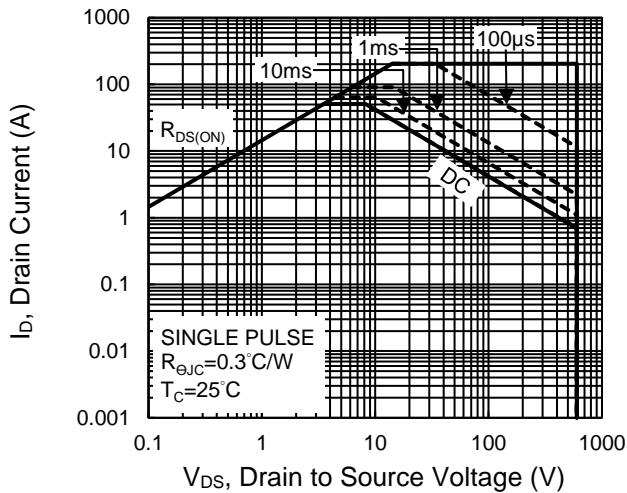
Capacitance vs. Drain-Source Voltage



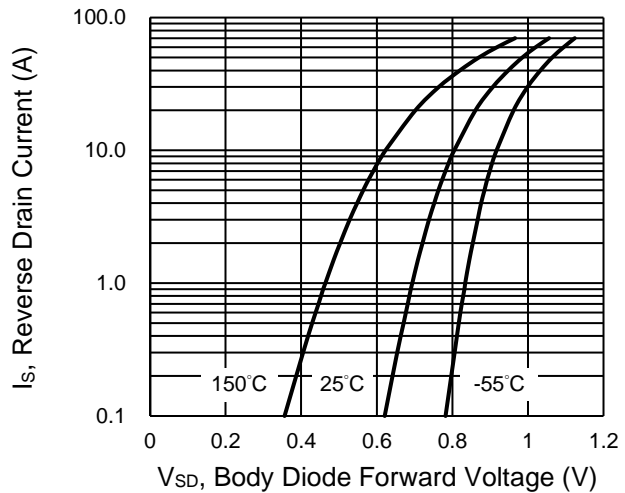
BV_{DSS} vs. Junction Temperature



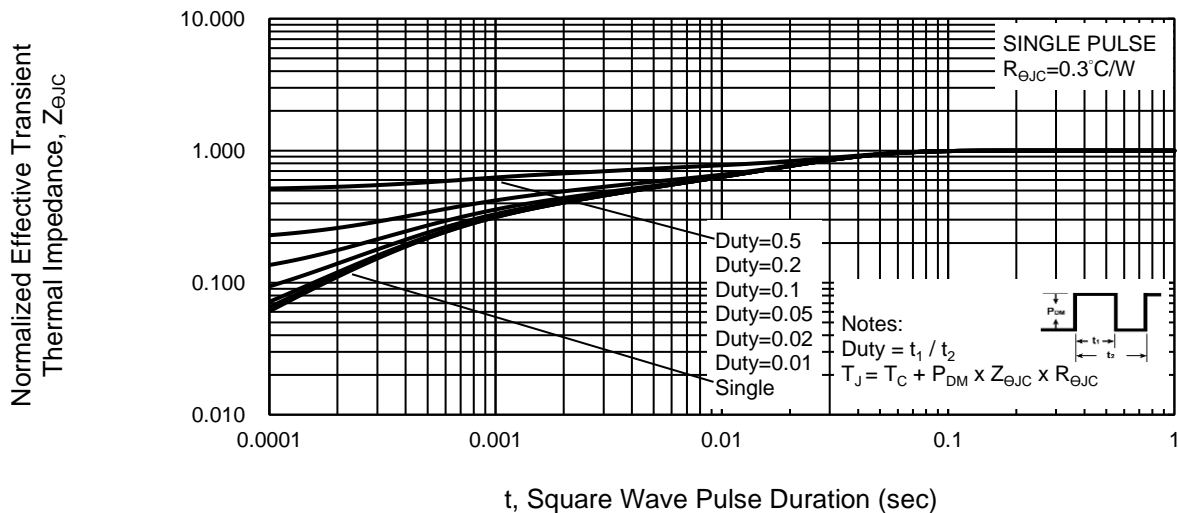
Maximum Safe Operating Area, Junction-to-Case



Source-Drain Diode Forward Current vs. Voltage



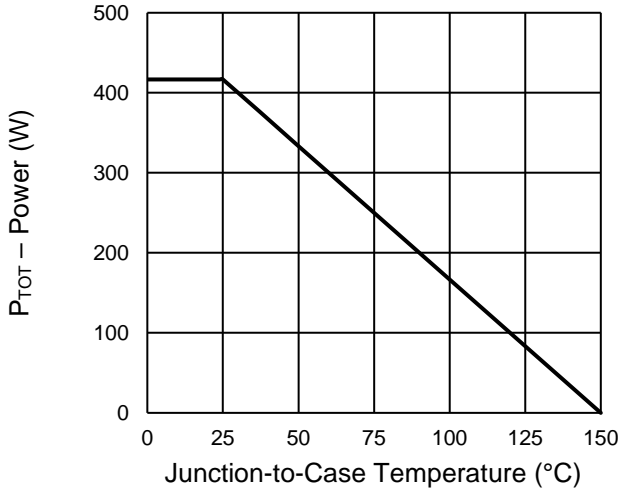
Normalized Thermal Transient Impedance, Junction-to-Case



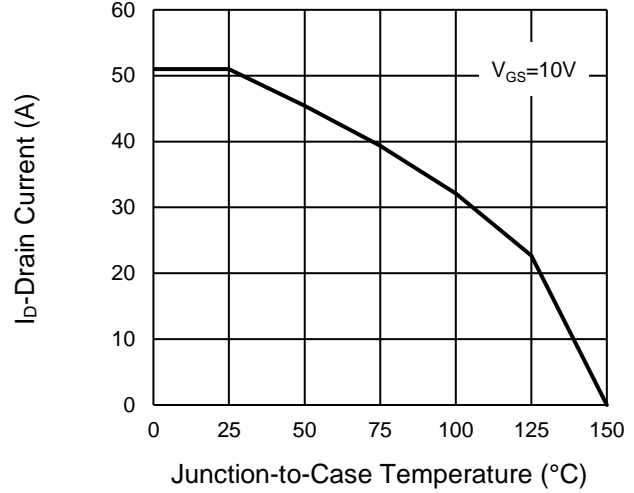
CHARACTERISTICS CURVES

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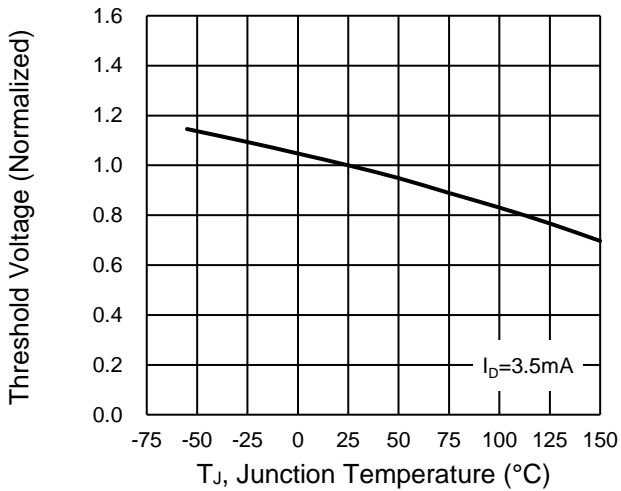
Power Dissipation



Drain Current

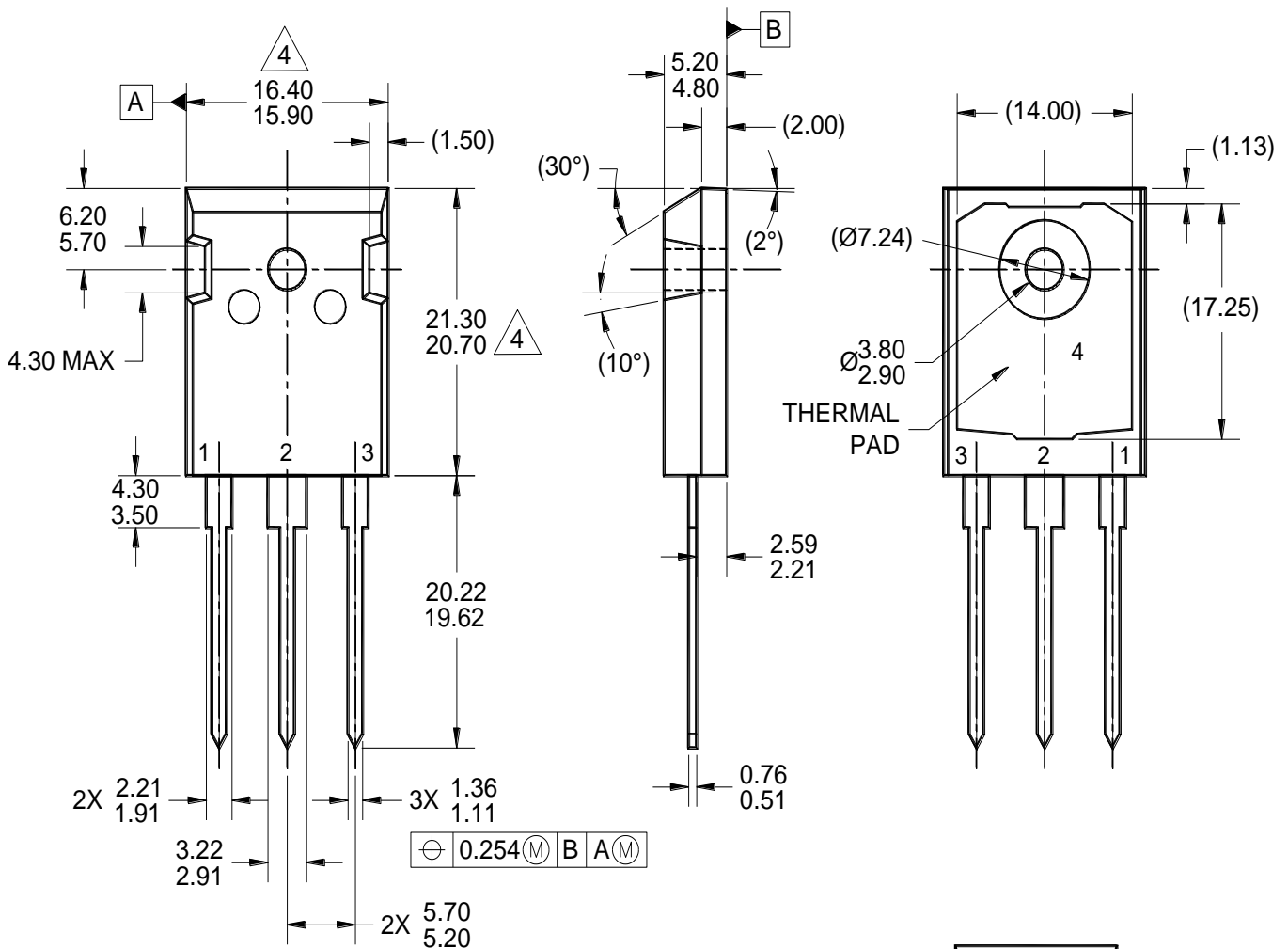


Normalized gate threshold voltage vs Temperature



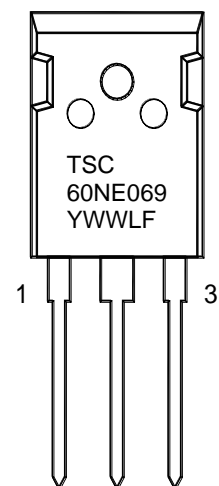
PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

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NOTES: UNLESS OTHERWISE SPECIFIED

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PACKAGE OUTLINE REFERENCE: JEDEC TO-247, VARIATION AD, ISSUE E.
4. MOLDED PLASTIC BODY DIMENSIONS DO NOT INCLUDE MOLD FLASH. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREME OF THE PLASTIC BODY.
5. DWG NO. REF: HQ2SD07-TO247AD-071 REV C.



MARKING DIAGRAM

- Y = YEAR CODE
- WW = WEEK CODE (01~52)
- L = LOT CODE (1~9, A~Z)
- F = FACTORY CODE

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